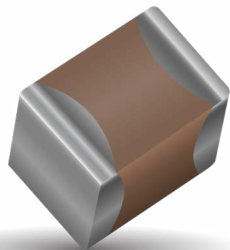


RF/Microwave Capacitors

RF/Microwave Multilayer Capacitors (MLC)

900C Series X7R Ceramic RF Power Multilayer Capacitors



GENERAL DESCRIPTION

KYOCERA AVX, the industry leader, offers new improved ESR/ESL performance for the 900 C Series RF Capacitors. This Series exhibits superior volumetric efficiency, providing high levels of capacitance for HF/ RF power applications. Ceramic construction provides a rugged, hermetic package.

KYOCERA AVX offers an encapsulation option for applications requiring extended protection against arc-over and corona.

FEATURES

- Case C Size (.250" x .250")
- Low ESR / ESL
- Rugged Construction
- Encapsulation Option Available *
- Capacitance Range 0.01 μ F to 1 μ F
- Mid-K
- High Reliability

FUNCTIONAL APPLICATIONS

- Bypass
- DC Blocking
- Coupling

TYPICAL CIRCUIT APPLICATIONS

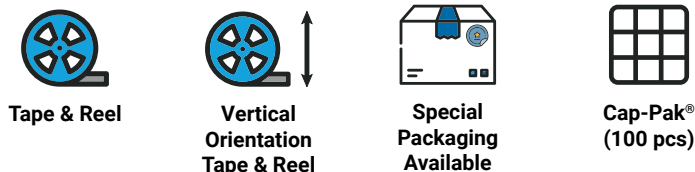
- HF/RF Power Amplifiers
- High Frequency Switch Mode Power Supplies
- Medical Electronics.

*For leaded styles only.

ENVIRONMENTAL CHARACTERISTICS

| | |
|-----------------------------|--|
| Thermal Shock | MIL-STD-202, Method 107, Condition A. |
| Moisture Resistance | MIL-STD-202, Method 106. |
| Low Voltage Humidity | MIL-STD-202, Method 103, Condition A, with 1.5 Volts DC applied while subjected to an environment of 85°C with 85% relative humidity for 240 hours min. |
| Life Test | MIL-STD-202, Method 108, for 2000 hours, at 125°C. 200% WVDC applied. |
| Solderability | Mil-STD-202, Method 208 |
| Terminal Strength | Terminations for chips and pellets withstand a pull of 5 lbs. min., 10 lbs. typical, for 5 seconds in direction perpendicular to the termination surface of the capacitor. |

PACKAGING OPTIONS



ELECTRICAL SPECIFICATIONS

| | |
|---|---|
| Dissipation Factor (DF) | 2.5% max. at 1 KHz |
| Temperature Coefficient of Capacitance (Tcc) | Less than $\pm 15\%$ (-55°C to +125°C) |
| Insulation Resistance (IR) | 0.01 MFd to 1 MFd 1000 megohms min. @ +25°C at rated WVDC. 100 megohms min. @ +125°C at rated WVDC. |
| Working Voltage (WVDC) | See Capacitance Values Table |
| Dielectric Withstanding Voltage (DWV) | Case C: 250% of rated WVDC for 5 secs. |
| Aging Effects | 3% maximum per decade hour |
| Piezoelectric Effects | Negligible |
| Dielectric Absorption | 2% typical |
| Operating Temperature Range | -55°C to +125°C (No derating of working voltage) |
| Termination Styles | Available in various surface mount and leaded styles. See Mechanical Configurations |
| Terminal Strength | Terminations for chips and pellets withstand a pull of 10 lbs. min., 15 lbs. typical, for 5 seconds in direction perpendicular to the termination surface of the capacitor. Test per MIL-STD-202, method 211. |

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CAPACITANCE VALUES

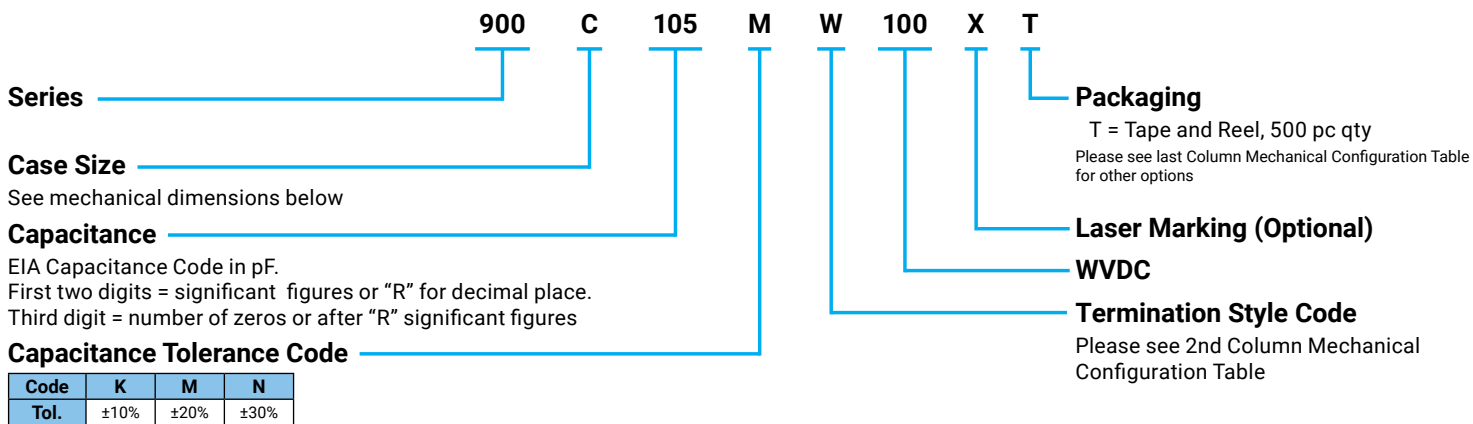
| Cap. Code | Cap. (Mfd) | Tol. | Rated Wvdc |
|-----------|------------|---------|------------|
| 103 | .010 | K, M, N | 300 |
| 153 | .015 | | 300 |
| 223 | .022 | | 300 |
| 333 | .033 | | 250 |
| 473 | .047 | | 250 |
| 683 | .068 | | 250 |
| 104 | .10 | | 200 |
| 154 | .15 | | 200 |
| 224 | .22 | | 200 |
| 334 | .33 | | 150 |
| 474 | .47 | | 150 |
| 684 | .68 | | 150 |
| 824 | .82 | | 100 |
| 105 | 1.0 | | 100 |

| Code | K | M | N |
|------|------|------|------|
| Tol. | ±10% | ±20% | ±30% |

VRMS = 0.707 X WVDC

- SPECIAL VALUES, TOLERANCES, HIGHER WVDC AND MATCHING AVAILABLE.
- ENCAPSULATION OPTION AVAILABLE. PLEASE CONSULT FACTORY.

HOW TO ORDER



The above part number refers to a 900 C Series (case size C) 1.0 MFd capacitor, M tolerance (±20%), 100 WVDC, with W termination (Tin/Lead, Solder Plated over Nickel Barrier), laser marking and ATC Matrix Tray packaging.

RF/Microwave Capacitors

RF/Microwave Multilayer Capacitors (MLC)

900C Series X7R Ceramic RF Power Multilayer Capacitors



MECHANICAL CONFIGURATIONS

| Series & Case Size | Term. Code | Case Size & Type | Outlines W/T Is A Termination Surface | Body Dimensions Inches (Mm) | | | Lead And Termination Dimensions And Materials | | Pkg Type & Qty | Pkg Code |
|--------------------|------------|---------------------------------|---------------------------------------|---|---|---|---|---|-------------------------|----------|
| | | | | Length (L) | Width (W) | Thickness (T) | Overlap (Y) | Materials | | |
| 900C | W | Solder Plate | | .230+.020 -.010 (5.84 +0.51 -0.25) | .250 ±.015 (6.35 ±0.38) | .145 (3.68) max. for capacitance values < 0.82 MFd; | .040 (1.02) max. | Tin/Lead, Solder Plated over Nickel Barrier Termination | T & R 500 Cap PaK 36 | T C36 |
| 900C | P | Pellet | | .230+.025 -.010 (5.84 +0.64 -0.25) | | | | Heavy Tin/Lead Coated, over Nickel Barrier Termination | T & R 500 Cap PaK 36 | T C36 |
| 900C | T | Solderable Nickel Barrier | | .230 +.020 -.010 (5.84 +0.51 -0.25) | | | | RoHS Compliant Tin Plated over Nickel Barrier Termination | T & R 500 Cap PaK 36 | T C36 |
| 900C | MS | Microstrip | | .245 ±.025 (6.22 ±0.64) | .165 (4.19) max. for capacitance values ≥ 0.82 MFd. | N/A | High Purity Silver Leads LL = .500 (12.7) min. WL = .240 ±.005 (6.10 ±.127) TL = .004 ±.001 (.102 ±.025) Leads are Attached with High Temperature Solder. | Cap Pak 24 | C24 | |
| 900C | AR | Axial Ribbon | | | | | Silver-plated Copper Leads LL = 1.0 (25.4) min. Dia. = .032 ±.002 (0.81 ±0.05) | Cap Pak 24 | C24 | |
| 900C | AW | Axial Wire | | .245 ±.025 (6.22 ±0.64) | .165 (4.19) max. for capacitance values ≥ 0.82 MFd. | N/A | Silver Leads LL = .500 (12.7) min. WL = * See below TL = .004 ±.001 (.102 ±.025) | Cap Pak 24 | C24 | |
| 900C | VA | Vertical Axial Ribbon | | | | | Silver-plated Copper Leads LL = 1.0 (25.4) min. Dia. = .032 ±.002 (0.81 ±0.05) | Cap Pak 24 | C24 | |
| 900C | RW | Radial Wire | | | | | | | | |

Custom lead styles and lengths are available; consult factory. All leads are high purity silver attached with high temperature solder and are RoHS compliant.

** WL = .110 (2.79) for capacitance values < 0.82 MFd.; WL = .130 (3.30) for capacitance values ≥ 0.82 MFd.


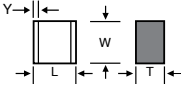

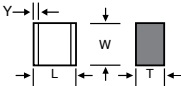
RF/Microwave Capacitors

RF/Microwave Multilayer Capacitors (MLC)

900C Series X7R Ceramic RF Power Multilayer Capacitors

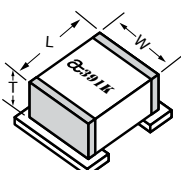


NON-MAGNETIC MECHANICAL CONFIGURATIONS

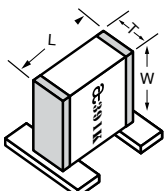
| Series & Case Size | Term. Code | Case Size & Type | Outlines W/T Is A Termination Surface | Body Dimensions Inches (Mm) | | | Lead And Termination Dimensions And Materials | | Pkg Type & Qty | Pkg Code |
|--------------------|------------|---|---|--|----------------------------|---|---|---|----------------------|----------|
| | | | | Length (L) | Width (W) | Thickness (T) | Overlap (Y) | Materials | | |
| 900C | WN |  Non-Mag Solder Plate |  | .230 +.025 -.010 (5.84 + 0.64-0.25) | .250 ±.015 (6.35 ±0.38) | .145 (3.68) max. < 0.82 MFd .165 (4.19) max. ≥0.82 MFd | .040 (1.02) max. | Tin/Lead, Solder Plated over Non-Magnetic Barrier Termination | T & R 500 Cap PaK 36 | T C36 |
| 900C | TN |  Non-Mag Solderable Barrier |  | .230 +.025 -.010 (5.84 + 0.64-0.25) | | | | RoHS Compliant Tin Plated over Non-Magnetic Barrier Termination | T & R 500 Cap PaK 36 | T C36 |

Custom lead styles and lengths are available; consult factory. All leads are high purity silver attached with high temperature solder and are RoHS compliant. 105M 105M

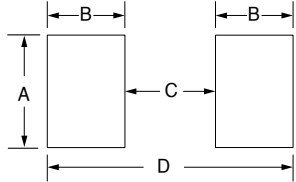
SUGGESTED MOUNTING PAD DIMENSIONS



Horizontal
Electrode Orientation



Vertical
Electrode Orientation



| Case C Vertical Mount | | | | | |
|-----------------------|--------------|--------|--------|--------|--------|
| Cap Value | Pad Size | A Min. | B Min. | C Min. | D Min. |
| < .82 μF | Normal | .150 | .050 | .200 | .300 |
| | High Density | .130 | .030 | .200 | .260 |
| ≥ .82 μF | Normal | .185 | .050 | .200 | .300 |
| | High Density | .165 | .030 | .200 | .260 |

| Horizontal Mount | | | | | |
|------------------|--------------|--------|--------|--------|--------|
| All Values | Pad Size | A Min. | B Min. | C Min. | D Min. |
| All Values | Normal | .150 | .050 | .200 | .300 |
| | High Density | .130 | .030 | .200 | .260 |